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4-Mbit (256K × 16) Static RAM

Features

- Very high speed: 45 ns
- Temperature range
 - Industrial: -40 °C to +85 °C
- Wide voltage range: 2.20 V to 3.60 V
- Ultra low standby power
 - Typical standby current: 2.5 μA
 - Maximum standby current: 7 μA (Industrial)
- Ultra low active power
 - Typical active current: 3.5 mA at f = 1 MHz
- Easy memory expansion with \overline{CE}_1 , CE_2 , and \overline{OE} Features
- Automatic power down when deselected
- Complementary metal oxide semiconductor (CMOS) for optimum speed and power
- Available in Pb-free 44-pin thin small outline package (TSOP) II package
- Byte power down feature

Functional Description

The CY621472E30 is a high performance CMOS static RAM (SRAM) organized as 256K words by 16 bits. This device features advanced circuit design to provide ultra low active current. It is ideal for providing More Battery Life™ (MoBL®) in portable applications such as cellular telephones. The device also has an automatic power down feature that significantly

reduces power consumption when addresses are not toggling. Placing the device into standby mode reduces power consumption by more than 99 percent when deselected (\overline{CE}_1 HIGH or CE_2 LOW or both \overline{BLE} and \overline{BHE} are HIGH). The input and output pins (I/O₀ through I/O₁₅) are placed in a high impedance state when:

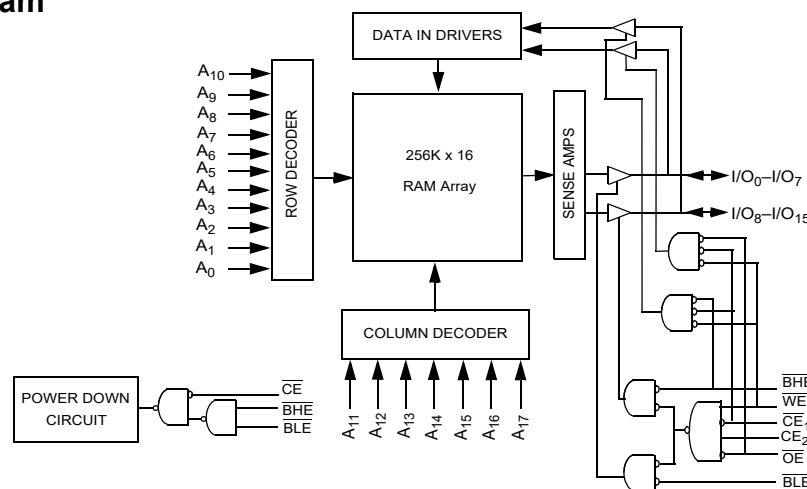
- Deselected (\overline{CE}_1 HIGH or CE_2 LOW)
- Outputs are disabled (\overline{OE} HIGH)
- Both Byte High Enable and Byte Low Enable are disabled (\overline{BHE} , \overline{BLE} HIGH)
- Write operation is active (\overline{CE}_1 LOW and CE_2 HIGH and \overline{WE} LOW)

To write to the device, take Chip Enable (\overline{CE}_1 LOW and CE_2 HIGH) and Write Enable (\overline{WE}) inputs LOW. If Byte Low Enable (\overline{BLE}) is LOW, then data from I/O pins (I/O₀ through I/O₇) is written into the location specified on the address pins (A₀ through A₁₇). If Byte High Enable (\overline{BHE}) is LOW, then data from I/O pins (I/O₈ through I/O₁₅) is written into the location specified on the address pins (A₀ through A₁₇).

To read from the device, take Chip Enable (\overline{CE}_1 LOW and CE_2 HIGH) and Output Enable (\overline{OE}) LOW while forcing the Write Enable (\overline{WE}) HIGH. If Byte Low Enable (\overline{BLE}) is LOW, then data from the memory location specified by the address pins appear on I/O₀ to I/O₇. If Byte High Enable (\overline{BHE}) is LOW, then data from memory appears on I/O₈ to I/O₁₅. See the [Truth Table on page 11](#) for a complete description of read and write modes.

For a complete list of related documentation, [click here](#).

Logic Block Diagram



Contents

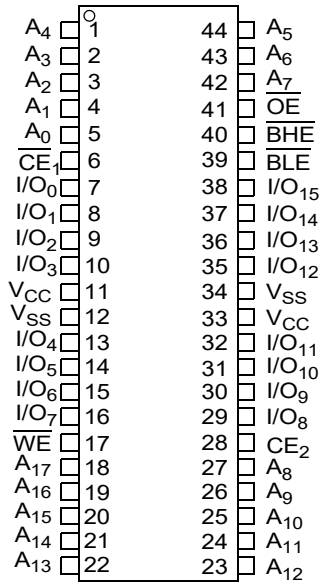
Product Portfolio	3	Ordering Information	12
Pin Configuration	3	Ordering Code Definitions	12
Maximum Ratings	4	Package Diagram	13
Operating Range	4	Acronyms	14
Electrical Characteristics	4	Document Conventions	14
Capacitance	5	Units of Measure	14
Thermal Resistance	5	Document History Page	15
AC Test Loads and Waveforms	5	Sales, Solutions, and Legal Information	16
Data Retention Characteristics	6	Worldwide Sales and Design Support	16
Data Retention Waveform	6	Products	16
Switching Characteristics	7	PSoC® Solutions	16
Switching Waveforms	8	Cypress Developer Community	16
Truth Table	11	Technical Support	16

Product Portfolio

Product	Range	V _{CC} Range (V)			Speed (ns)	Power Dissipation					
						Operating I _{CC} (mA)				Standby I _{SB2} (μA)	
		f = 1 MHz		f = f _{max}							
		Typ ^[1]	Max	Typ ^[1]		Max	Typ ^[1]	Max			
CY621472E30LL	Industrial	2.2	3.0	3.6	45	3.5	6	15	20	2.5	7

Pin Configuration

Figure 1. 44-pin TSOP II pinout



Note

1. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at V_{CC} = V_{CC(typ)}, T_A = 25 °C.

Maximum Ratings

Exceeding the maximum ratings may impair the useful life of the device. User guidelines are not tested.

Storage temperature -65 °C to +150 °C

Ambient temperature with power applied -55 °C to +125 °C

Supply voltage to ground potential -0.3 V to +3.9 V ($V_{CCmax} + 0.3$ V)

DC Voltage Applied to Outputs in High Z State ^[2, 3] -0.3 V to 3.9 V ($V_{CCmax} + 0.3$ V)

DC input voltage ^[2, 3] -0.3 V to 3.9 V ($V_{CCmax} + 0.3$ V)

Output current into outputs (LOW) 20 mA

Static discharge voltage (MIL-STD-883, Method 3015) > 2001 V

Latch up current..... > 200 mA

Operating Range

Device	Range	Ambient Temperature	V_{CC} ^[4]
CY621472E30LL	Industrial	-40 °C to +85 °C	2.2 V to 3.6 V

Electrical Characteristics

Over the Operating Range

Parameter	Description	Test Conditions	45 ns			Unit
			Min	Typ ^[5]	Max	
V_{OH}	Output HIGH voltage	$I_{OH} = -0.1$ mA	2.0	–	–	V
		$I_{OH} = -1.0$ mA, $V_{CC} \geq 2.70$ V	2.4	–	–	V
V_{OL}	Output LOW voltage	$I_{OL} = 0.1$ mA	–	–	0.4	V
		$I_{OL} = 2.1$ mA, $V_{CC} = 2.70$ V	–	–	0.4	V
V_{IH}	Input HIGH voltage	$V_{CC} = 2.2$ V to 2.7 V	1.8	–	$V_{CC} + 0.3$	V
		$V_{CC} = 2.7$ V to 3.6 V	2.2	–	$V_{CC} + 0.3$	V
V_{IL}	Input LOW voltage	$V_{CC} = 2.2$ V to 2.7 V	-0.3	–	0.6	V
		$V_{CC} = 2.7$ V to 3.6 V	-0.3	–	0.8	V
I_{IX}	Input leakage current	$GND \leq V_I \leq V_{CC}$	-1	–	+1	μ A
I_{OZ}	Output leakage current	$GND \leq V_O \leq V_{CC}$, Output Disabled	-1	–	+1	μ A
I_{CC}	V_{CC} operating supply current	$f = f_{max} = 1/t_{RC}$	–	15	20	mA
		$f = 1$ MHz	–	3.5	6	
I_{SB1} ^[6]	Automatic CE power-down current – CMOS inputs	$\overline{CE}_1 \geq V_{CC} - 0.2$ V, $CE_2 \leq 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V, $V_{IN} \leq 0.2$ V, $f = f_{max}$ (address and data only), $f = 0$ (\overline{OE} , \overline{BHE} , \overline{BLE} and \overline{WE}), $V_{CC} = 3.60$ V	–	2.5	7	μ A
I_{SB2} ^[6]	Automatic CE Power down current – CMOS inputs	$\overline{CE}_1 \geq V_{CC} - 0.2$ V or $CE_2 \leq 0.2$ V or $(\overline{BHE}$ and $\overline{BLE}) \geq V_{CC} - 0.2$ V, $V_{IN} \geq V_{CC} - 0.2$ V or $V_{IN} \leq 0.2$ V, $f = 0$, $V_{CC} = 3.60$ V	–	2.5	7	μ A

Notes

- $V_{IL(min)}$ = -2.0 V for pulse durations less than 20 ns.
- $V_{IH(max)}$ = $V_{CC} + 0.75$ V for pulse durations less than 20 ns.
- Full device AC operation assumes a minimum of 100 μ s ramp time from 0 to $V_{CC(min)}$ and 200 μ s wait time after V_{CC} stabilization.
- Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(typ)}$, $T_A = 25$ °C.
- Chip enables (\overline{CE}_1 and CE_2) need to be tied to CMOS levels to meet the $I_{SB1}/I_{SB2}/I_{CCDR}$ spec. Other inputs can be left floating.

Capacitance

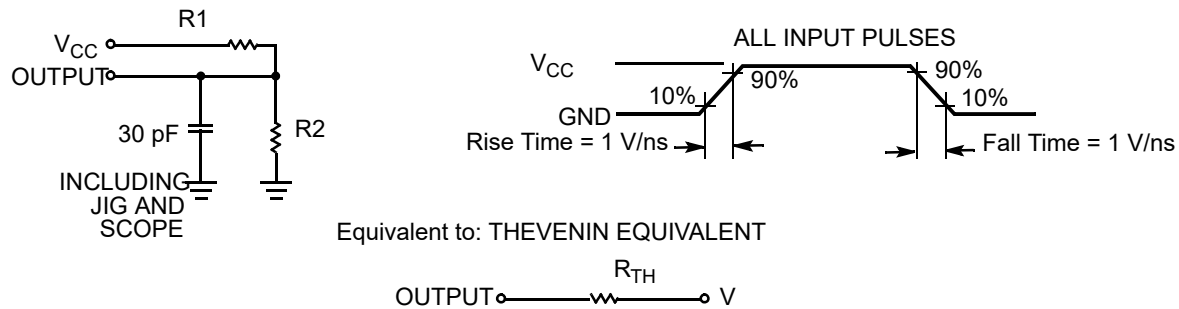
Parameter ^[7]	Description	Test Conditions	Max	Unit
C _{IN}	Input capacitance	T _A = 25 °C, f = 1 MHz, V _{CC} = V _{CC(typ)}	10	pF
C _{OUT}	Output capacitance		10	pF

Thermal Resistance

Parameter ^[7]	Description	Test Conditions	44-pin TSOP II Package	Unit
Θ _{JA}	Thermal resistance (junction to ambient)	Still Air, soldered on a 3 × 4.5 inch, two-layer printed circuit board	77	°C/W
Θ _{JC}	Thermal resistance (junction to case)		13	°C/W

AC Test Loads and Waveforms

Figure 2. AC Test Loads and Waveforms



Parameters	2.50 V	3.0 V	Unit
R1	16667	1103	Ω
R2	15385	1554	Ω
R _{TH}	8000	645	Ω
V _{TH}	1.20	1.75	V

Note

7. Tested initially and after any design or process changes that may affect these parameters.

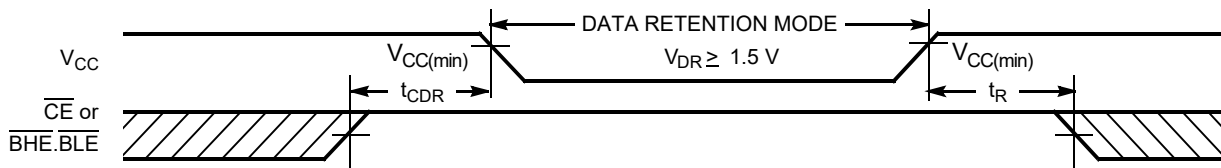
Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Typ ^[8]	Max	Unit
V_{DR}	V_{CC} for data retention		1.5	–	–	V
$I_{CCDR}^{[9]}$	Data retention current	$V_{CC} = 1.5\text{ V}$, $\overline{CE}_1 \geq V_{CC} - 0.2\text{ V}$ or $CE_2 \leq 0.2\text{ V}$ or $(\overline{BHE}$ and $\overline{BLE}) \geq V_{CC} - 0.2\text{ V}$, $V_{IN} \geq V_{CC} - 0.2\text{ V}$ or $V_{IN} \leq 0.2\text{ V}$	–	3	8.8	μA
$t_{CDR}^{[10]}$	Chip deselect to data retention time		0	–	–	ns
$t_R^{[11]}$	Operation recovery time		45	–	–	ns

Data Retention Waveform

Figure 3. Data Retention Waveform^[12, 13]



Notes

8. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(typ)}$, $T_A = 25\text{ }^\circ\text{C}$.

9. Chip enables (\overline{CE}_1 and CE_2) need to be tied to CMOS levels to meet the $I_{SB1} / I_{SB2} / I_{CCDR}$ spec. Other inputs can be left floating.

10. Tested initially and after any design or process changes that may affect these parameters.

11. Full device operation requires linear V_{CC} ramp from V_{DR} to $V_{CC(min)} \geq 100\text{ }\mu\text{s}$ or stable at $V_{CC(min)} \geq 100\text{ }\mu\text{s}$.

12. \overline{CE} refers to the internal logical combination of \overline{CE}_1 and CE_2 such that when \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW. For all other cases \overline{CE} is HIGH.

13. $\overline{BHE.BLE}$ is the AND of both \overline{BHE} and \overline{BLE} . Deselect the chip by either disabling the chip enable signals or by disabling both \overline{BHE} and \overline{BLE} .

Switching Characteristics

Over the Operating Range

Parameter ^[14]	Description	45 ns		Unit
		Min	Max	
Read Cycle				
t_{RC}	Read cycle time	45	–	ns
t_{AA}	Address to data valid	–	45	ns
t_{OHA}	Data hold from address change	10	–	ns
t_{ACE}	\overline{CE}_1 LOW/ CE_2 HIGH to data valid	–	45	ns
t_{DOE}	\overline{OE} LOW to data valid	–	22	ns
t_{LZOE}	\overline{OE} LOW to Low Z ^[15]	5	–	ns
t_{HZOE}	\overline{OE} HIGH to High Z ^[15, 16]	–	18	ns
t_{LZCE}	\overline{CE}_1 LOW/ CE_2 HIGH to Low Z ^[15]	10	–	ns
t_{HZCE}	\overline{CE}_1 HIGH/ CE_2 LOW to High Z ^[15, 16]	–	18	ns
t_{PU}	\overline{CE}_1 LOW/ CE_2 HIGH to Power-up	0	–	ns
t_{PD}	\overline{CE}_1 HIGH/ CE_2 LOW to Power-down	–	45	ns
t_{DBE}	$\overline{BLE}/\overline{BHE}$ LOW to data valid	–	45	ns
t_{LZBE}	$\overline{BLE}/\overline{BHE}$ LOW to Low Z ^[15, 17]	5	–	ns
t_{HZBE}	$\overline{BLE}/\overline{BHE}$ HIGH to High Z ^[15, 16]	–	18	ns
Write Cycle ^[18, 19]				
t_{WC}	Write cycle time	45	–	ns
t_{SCE}	\overline{CE}_1 LOW/ CE_2 HIGH to Write End	35	–	ns
t_{AW}	Address setup to write end	35	–	ns
t_{HA}	Address hold from write end	0	–	ns
t_{SA}	Address setup to write start	0	–	ns
t_{PWE}	\overline{WE} pulse width	35	–	ns
t_{BW}	$\overline{BLE}/\overline{BHE}$ LOW to write end	35	–	ns
t_{SD}	Data setup to write end	25	–	ns
t_{HD}	Data hold from write end	0	–	ns
t_{HZWE}	\overline{WE} LOW to High Z ^[15, 16]	–	18	ns
t_{LZWE}	\overline{WE} HIGH to Low Z ^[15]	10	–	ns

Notes

14. Test conditions for all parameters other than tri-state parameters assume signal transition time of 3 ns (1 V/ns) or less, timing reference levels of $V_{CC(typ)}/2$, input pulse levels of 0 to $V_{CC(typ)}$, and output loading of the specified I_{OL}/I_{OH} as shown in the [Figure 2 on page 5](#).
15. At any temperature and voltage condition, t_{HZCE} is less than t_{LZCE} , t_{HZBE} is less than t_{LZBE} , t_{HZOE} is less than t_{LZOE} , and t_{HZWE} is less than t_{LZWE} for any device.
16. t_{HZOE} , t_{HZCE} , t_{HZBE} , and t_{HZWE} transitions are measured when the outputs enter a high impedance state.
17. If both byte enables are together, this value is 10 ns.
18. The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} , \overline{BLE} , or both = V_{IL} . All signals must be active to initiate a write and any of these signals can terminate a write by going inactive. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
19. The minimum write cycle pulse width for WRITE Cycle 4 (\overline{WE} controlled, \overline{OE} LOW) should be equal to the sum of t_{HZWE} and t_{SD} .

Switching Waveforms

Figure 4. Read Cycle No. 1 (Address Transition Controlled) [20, 21]

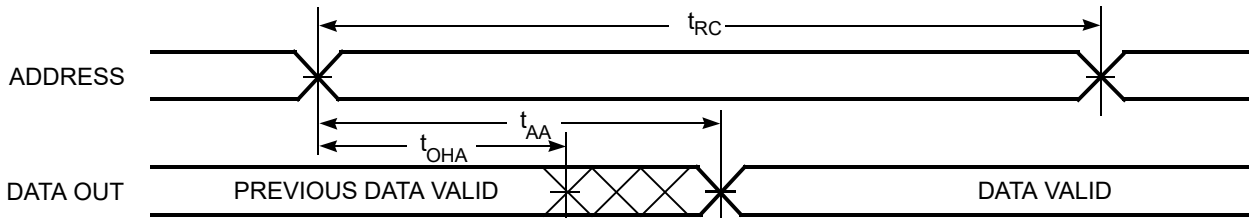
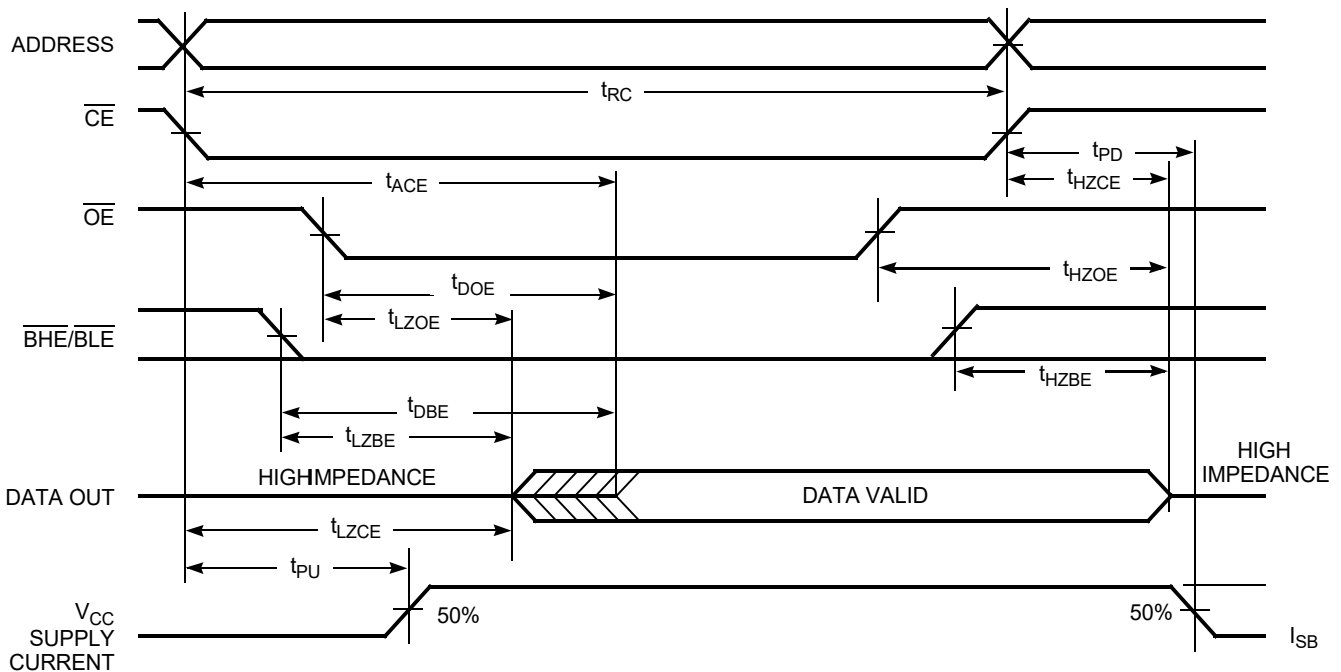


Figure 5. Read Cycle No. 2 (\overline{OE} Controlled) [21, 22, 23]



Notes

- 20. The device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$, \overline{BHE} , \overline{BLE} , or both = V_{IL} .
- 21. \overline{WE} is HIGH for read cycle.
- 22. \overline{CE} refers to the internal logical combination of \overline{CE}_1 and CE_2 such that when \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW. For all other cases \overline{CE} is HIGH.
- 23. Address valid before or similar to \overline{CE} and \overline{BHE} , \overline{BLE} transition LOW.

Switching Waveforms (continued)

Figure 6. Write Cycle No. 1 (\overline{WE} Controlled) [24, 25, 26, 27]

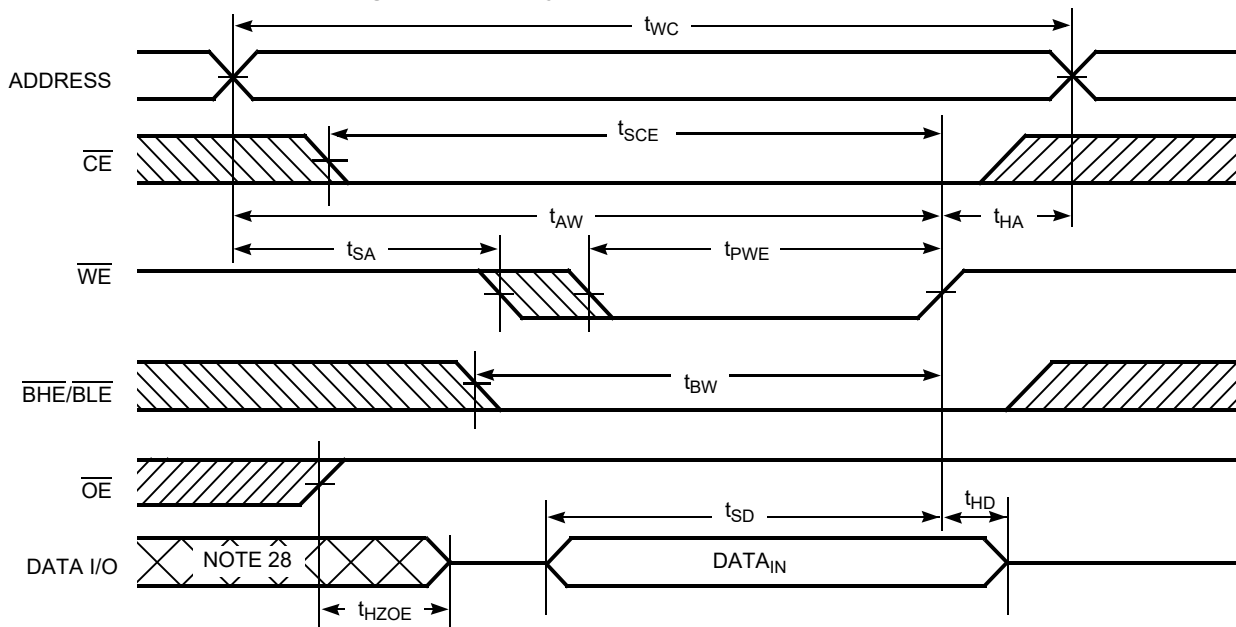
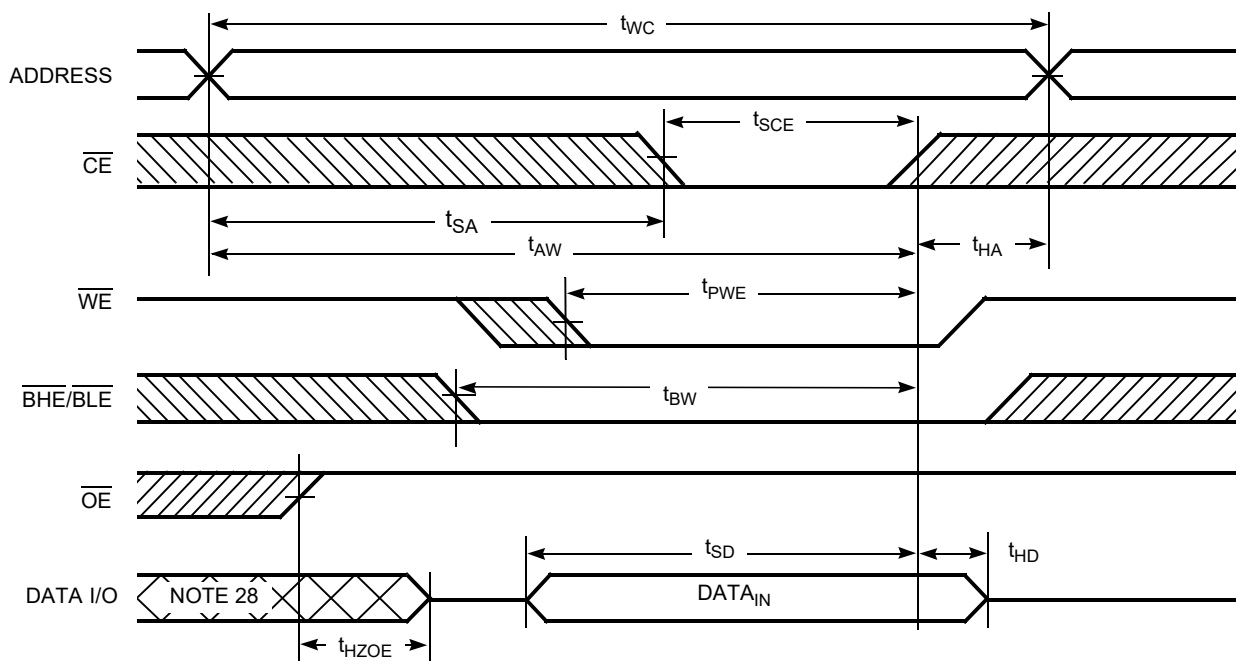


Figure 7. Write Cycle No. 2 (\overline{CE} Controlled) [24, 25, 26, 27]



Notes

- 24. \overline{CE} refers to the internal logical combination of \overline{CE}_1 and CE_2 such that when \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW. For all other cases \overline{CE} is HIGH.
- 25. The internal write time of the memory is defined by the overlap of \overline{WE} , $\overline{CE} = V_{IL}$, \overline{BHE} , \overline{BLE} , or both = V_{IL} . All signals must be active to initiate a write and any of these signals can terminate a write by going inactive. The data input setup and hold timing must be referenced to the edge of the signal that terminates the write.
- 26. Data I/O is high impedance if $\overline{OE} = V_{IH}$.
- 27. If \overline{CE} goes HIGH simultaneously with $\overline{WE} = V_{IH}$, the output remains in a high impedance state.
- 28. During this period, the I/Os are in output state. Do not apply input signals.

Switching Waveforms (continued)

Figure 8. Write Cycle No. 3 (\overline{WE} Controlled, \overline{OE} LOW) [29, 30, 31]

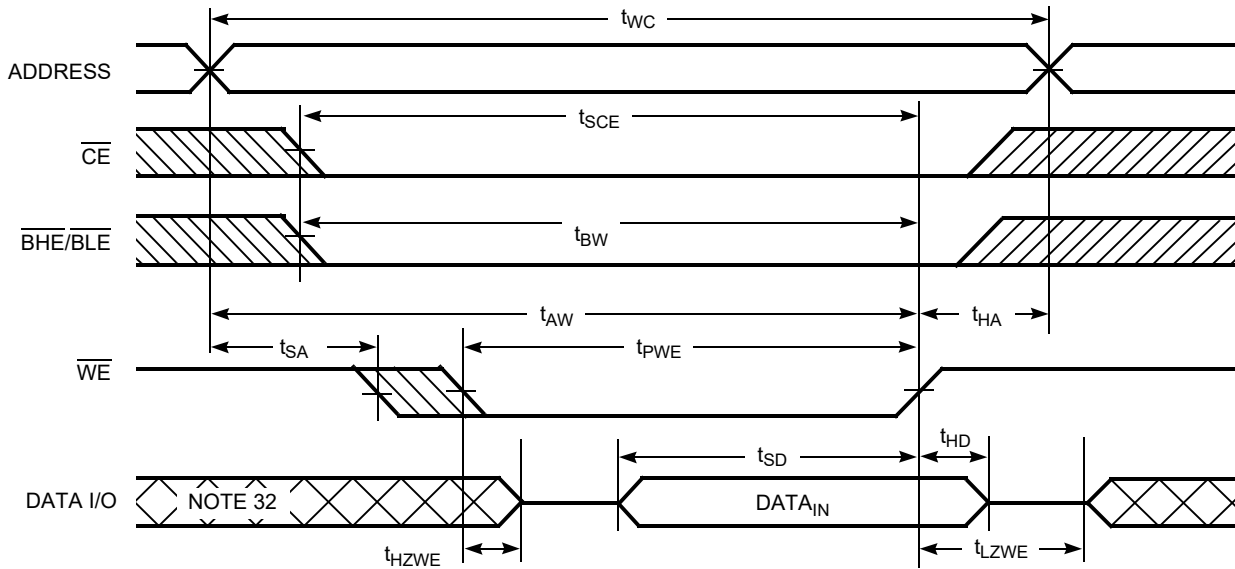
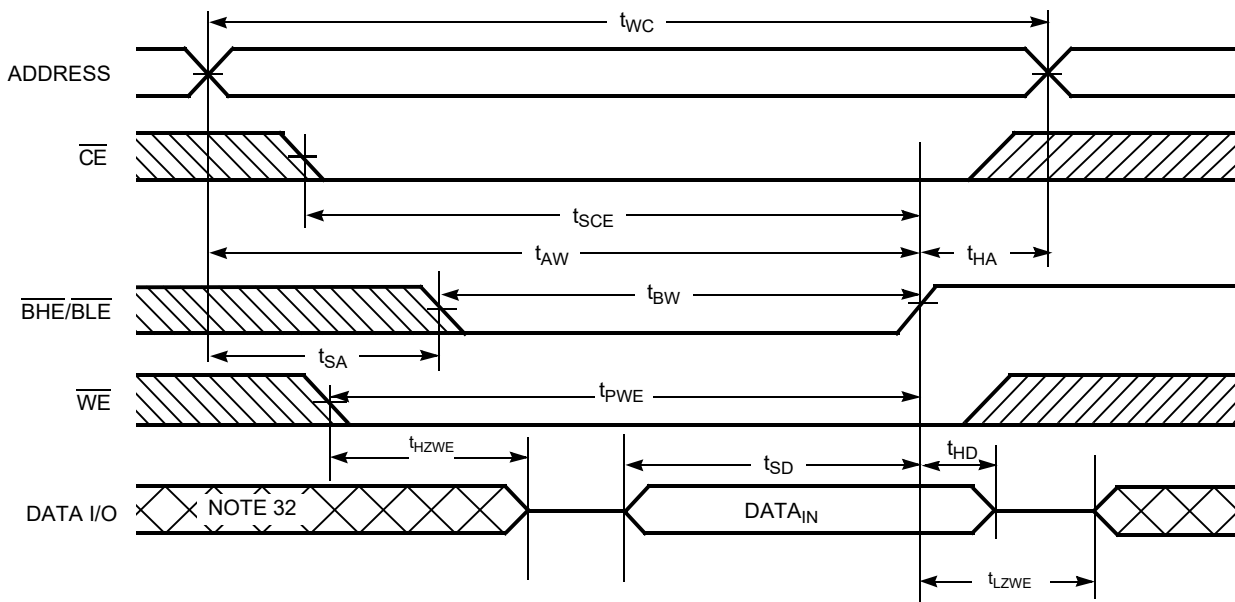


Figure 9. Write Cycle No. 4 ($\overline{BHE}/\overline{BLE}$ Controlled, \overline{OE} LOW) [29, 30]



Notes

- 29. \overline{CE} refers to the internal logical combination of \overline{CE}_1 and CE_2 such that when \overline{CE}_1 is LOW and CE_2 is HIGH, \overline{CE} is LOW. For all other cases \overline{CE} is HIGH.
- 30. If \overline{CE} goes HIGH simultaneously with $WE = V_{IH}$, the output remains in a high impedance state.
- 31. The minimum write cycle pulse width should be equal to the sum of t_{HZWE} and t_{SD} .
- 32. During this period, the I/Os are in output state. Do not apply input signals.

Truth Table

\overline{CE}_1	CE_2	\overline{WE}	\overline{OE}	\overline{BHE}	\overline{BLE}	I/Os	Mode	Power
H	X ^[33]	X	X	X	X	High Z	Deselect/Power-down	Standby (I_{SB})
X ^[33]	L	X	X	X	X	High Z	Deselect/Power-down	Standby (I_{SB})
X ^[33]	X ^[33]	X	X	H	H	High Z	Deselect/Power-down	Standby (I_{SB})
L	H	H	L	L	L	Data out (I/O ₀ –I/O ₁₅)	Read	Active (I_{CC})
L	H	H	L	H	L	Data out (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High Z	Read	Active (I_{CC})
L	H	H	L	L	H	Data out (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High Z	Read	Active (I_{CC})
L	H	H	H	L	L	High Z	Output disabled	Active (I_{CC})
L	H	H	H	H	L	High Z	Output disabled	Active (I_{CC})
L	H	H	H	L	H	High Z	Output disabled	Active (I_{CC})
L	H	L	X	L	L	Data in (I/O ₀ –I/O ₁₅)	Write	Active (I_{CC})
L	H	L	X	H	L	Data in (I/O ₀ –I/O ₇); I/O ₈ –I/O ₁₅ in High Z	Write	Active (I_{CC})
L	H	L	X	L	H	Data in (I/O ₈ –I/O ₁₅); I/O ₀ –I/O ₇ in High Z	Write	Active (I_{CC})

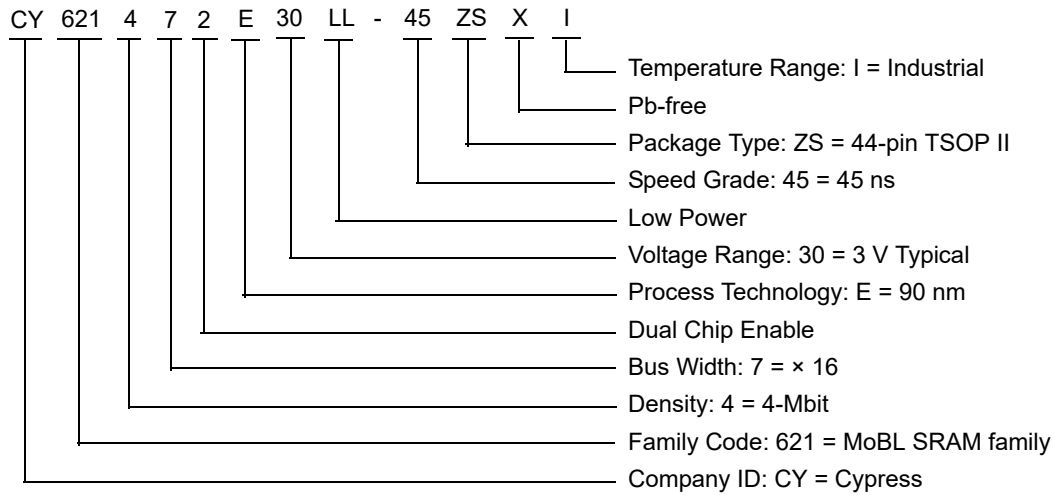
Note

33. The 'X' (Don't care) state for the chip enables (\overline{CE}_1 and CE_2) in the truth table refer to the logic state (either HIGH or LOW). Intermediate voltage levels on these pins is not permitted.

Ordering Information

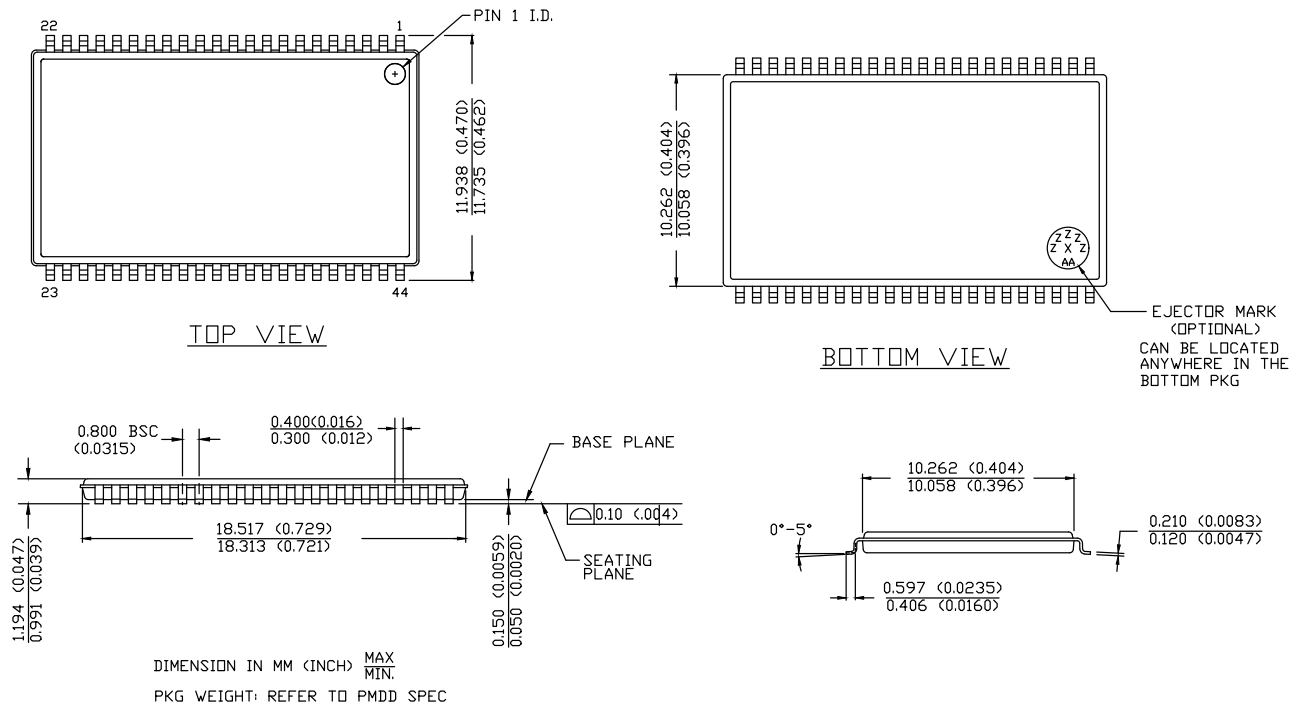
Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
45	CY621472E30LL-45ZSXI	51-85087	44-pin TSOP II (Pb-free)	Industrial

Ordering Code Definitions



Package Diagram

Figure 10. 44-pin TSOP II (18.4 × 10.2 × 1.194 mm) Package Outline, 51-85087



51-85087 *F

Acronyms

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
I/O	Input/Output
OE	Output Enable
SRAM	Static Random Access Memory
TSOP	Thin Small Outline Package
WE	Write Enable

Document Conventions

Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
MHz	megahertz
μA	microampere
μs	microsecond
mA	milliampere
ns	nanosecond
Ω	ohm
%	percent
pF	picofarad
V	volt
W	watt

Document History Page

Document Title: CY621472E30 MoBL, 4-Mbit (256K × 16) Static RAM Document Number: 001-67798			
Rev.	ECN No.	Submission Date	Description of Change
**	3184883	03/01/2011	New data sheet.
*A	3223503	04/15/2011	Updated Truth Table : Removed overline bar for CE ₂ in column heading. Updated to new template.
*B	3261142	05/19/2011	Updated Switching Characteristics : Changed minimum value of t _{LZBE} parameter from 10 ns to 5 ns. Added Ordering Information and Ordering Code Definitions . Added Acronyms and Units of Measure .
*C	3365953	09/08/2011	Changed status from Preliminary to Final. Updated Package Diagram : spec 51-85087 – Changed revision from *C to *D.
*D	3414567	10/20/2011	Replaced CY62147EV30 with CY621472E30 in all instances across the document.
*E	4331825	04/03/2014	Updated Switching Characteristics : Added Note 19 and referred the same note in "Write Cycle". Updated Switching Waveforms : Added Note 31 and referred the same note in Figure 8 . Updated Package Diagram : spec 51-85087 – Changed revision from *D to *E. Updated to new template. Completing Sunset Review.
*F	4573121	11/18/2014	Updated Functional Description : Added "For a complete list of related documentation, click here ." at the end.
*G	6906316	06/26/2020	Updated Features : Changed value of Typical standby current from 1 µA to 2.5 µA. Changed value of Typical active current from 2 mA to 3.5 mA. Updated Product Portfolio : Changed typical value of Operating I _{CC} from 2 mA to 3.5 mA corresponding to "f = 1 MHz". Changed maximum value of Operating I _{CC} from 2.5 mA to 6 mA corresponding to "f = 1 MHz". Changed typical value of Standby, I _{SB2} from 1 µA to 2.5 µA. Updated Electrical Characteristics : Changed typical value of I _{CC} parameter from 2 mA to 3.5 mA corresponding to Test Condition "f = 1 MHz". Changed maximum value of I _{CC} parameter from 2.5 mA to 6 mA corresponding to Test Condition "f = 1 MHz". Changed typical value of I _{SB1} parameter from 1 µA to 2.5 µA. Changed typical value of I _{SB2} parameter from 1 µA to 2.5 µA. Updated Data Retention Characteristics : Changed typical value of I _{CCDR} parameter from 0.8 µA to 3 µA. Changed maximum value of I _{CCDR} parameter from 7 µA to 8.8 µA. Updated Package Diagram : spec 51-85087 – Changed revision from *E to *F. Updated to new template.

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